

	SnPb Eutectic	Lead-free
Average ramp up rate (25°C to $T_P$ )	3°C/sec max	3°C/sec max
Preheat Range, $T_{Smin} - T_{Smax}$	100° to 150°C	150 to 200 C
Preheat time, $t_s$	60-120 secs	60-180 secs
Liquidus Temp, $T_L$	183°C	217°C
Time above liquidus temp, $t_L$	60-150 secs	60-150 secs
Peak temp, $T_P$	240° +0/-5°C	260° +0/-5°C
Time within 5C of the actual peak temp, $t_p$	10-30 secs	20-40 secs
Ramp down rate	6°C/sec max	6°C/sec max
Time to peak temp, $t_{25°C \text{ to Peak}}$	6 mins max	8 mins max

Table 1: Typical Reflow Profile Conditions Used for Package MSL Determination

Notes:

1. All temperatures refer to the topside of the package, measured on package body surface.
2. This profile is used for internal qualification of packages and only shows the times and temperatures our packages are guaranteed to withstand. This should not be construed as a recommended profile for board mounting of our parts. Customers should optimize their board mounting reflow profiles per their board design, solder paste and flux selection etc.

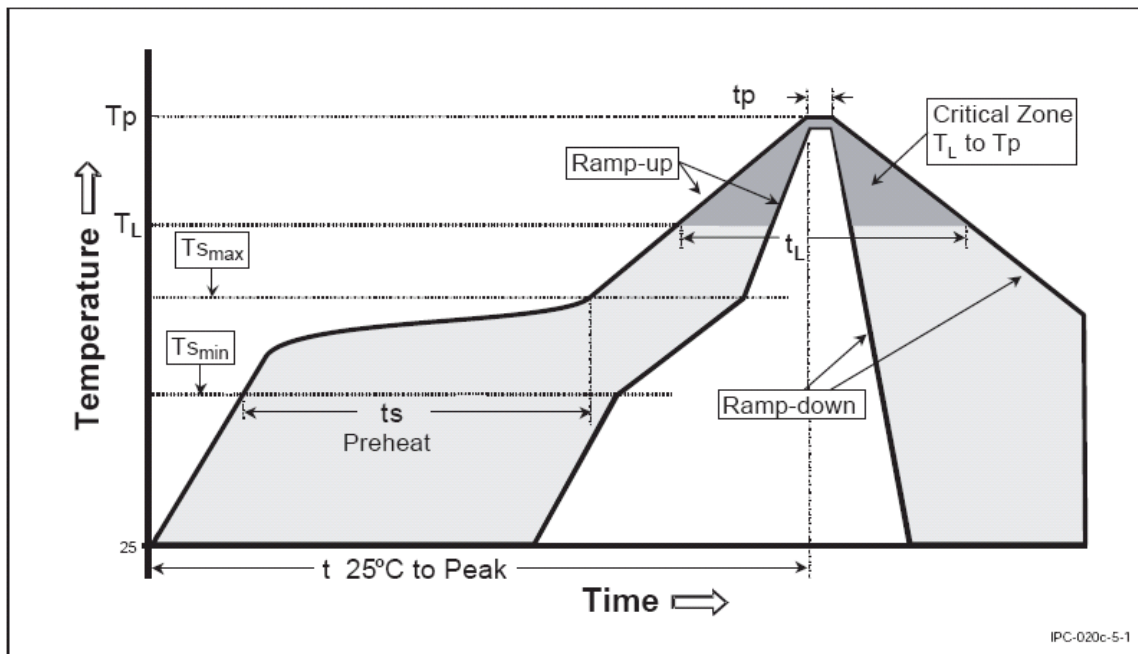


Table 1: Schematic of the Reflow Profile (Source: IPC/JEDEC J-STD-020C)